LINEAR TECHNOLOGY MATERIALS DECLARATION

lt8304hs8e#trpbf **(Engineering Calculation)** **SOIC Exposed Pad**

(printed on: 2020-07-11 20:43:41) **TOTAL MASS (g): 0.074998**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.002750**	**1000000**	**36667.6914062**
Die Coat	Dow Corning	Silicone	69430-27-9	**0.000000**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.023398	964450	311982.03125
		Iron (Fe)	7439-89-6	0.000547	22560	7293.53613281
		Phosphorus (P)	7723-14-0	0.000006	240	80.0022354126
		Zinc (Zn)	7440-66-6	0.000030	1250	400.011138916
		Nickel (Ni)	7440-02-0	0.000279	11500	3720.10375977
		Silicon (Si)	7440-21-3	0.000000	0	0
		Magnesium (Mg)	7439-95-4	0.000000	0	0
		Tin (Sn)	7440-31-5	0.000000	0	0
		Lead Frame Total:		**0.024260**	**1000000**	**323475.6875**
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
		Exter. Plating Sn	7440-31-5	0.001920	1000000	25599.4824219
		External Plating Total:		**0.001920**	**1000000**	**25599.4824219**
		Inter. Plating Ni	7440-02-0	0.000300	1000000	4000.11157227
		Inter. Plating Ag	7440-22-4	0.000000	0	0
		Internal Plating Total:		**0.000300**	**1000000**	**4000.11157227**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000902	750000	12027.0019531
		Tin (Sn)	7440-31-5	0.000000	0	0
		Lead (Pb)	7439-92-1	0.000000	0	0
		Silica (SiO2)	60676-86-0	0.000000	0	0
		Indium (In)	7440-74-6	0.000000	0	0
		Metal Oxide		0.000000	0	0
		Antimony (Sb)	7440-36-0	0.000000	0	0
		Resin (EP)		0.000301	250000	4013.4453125
		Die Attach Total:		**0.001203**	**1000000**	**16040.4462891**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004571	103000	60948.3671875
		Bromine (Br)	40039-93-8	0.000000	0	0
		Silica (SiO2)	60676-86-0	0.039720	895000	529614.75
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0
		Metal Hydroxide		0.000000	0	0
		Carbon Black (C)	1333-86-4	0.000089	2000	1186.69970703
		Encapsulation Total:		**0.044380**	**1000000**	**591749.875**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**0.000185**	**1000000**	**2466.73535156**
					TOTAL MASS (g):	**0.074998**